



July 2000

## Application Notes

- AN 71 Guidelines for Handling J-Lead & QFP Devices
- AN 80 Selecting Sockets for Altera Devices
- AN 81 Reflow Soldering Guidelines for Surface-Mount Devices
- AN 90 SameFrame Pin-Out Designs for FineLine BGA Packages
- AN 113 Plastic Package Reliability & Testing
- AN 114 Designing with FineLine BGA Packages

## Brochures

- Packaging Solutions Brochure

## Data Sheets

- Altera Device Package Information Data Sheet
- Configuration Elements Data Sheet
- QFP Carrier & Development Socket Data Sheet

## General Information

- Introduction (to the Altera *1999 Data Book*)
- Ordering Information
- Saving Board Space with MAX 7000S & MAX 7000A TQFP Packages